

**DDR3/DDR3L
ECC LRDIMM
VR7ELxx7254xHx
1.5V/1.35V**

The Viking Load Reduced DIMM (LRDIMM) provides a DDR3 JEDEC standard interface that is fully buffered to provide a single load per signal, per module. The buffer reduces the capacitive loading on the memory channel address, control, DQ and DQS nodes to enable large memory capacities at high memory bandwidths.

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 1 of 20

REVISION HISTORY

Revision	Release Date	Description of Change	Checked By (Full Name)
A	3/12/12	Remove Preliminary watermark	
A1	12/17/12	Add 32GB PN's	
A2	12/17/12	Add DDR3-1600 speed grade	
A3	1/2/14	Revised datasheet format	
B	10/21/16	Revise logo. Change company address	

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 2 of 20

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All printed circuit boards (PCBs) have a flammability rating of UL94V-0.

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 3 of 20

Ordering Information and Module Configuration

Viking Part Number	Voltage	Capacity	Module Configuration	Device Configuration	Device Package	Module Ranks	Performance	CAS Latency
VR7EL2G7254GHZ	1.5V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-6400	CL6 (6-6-6)
VR7EL2G7254GHA	1.5V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-8500	CL7 (7-7-7)
VR7EL2G7254GHD	1.5V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-10600	CL9 (9-9-9)
VR7EL2G7254GHF	1.5V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-12800	CL11 (11-11-11)
VR7EL4G7254HHZ	1.5V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-6400	CL6 (6-6-6)
VR7EL4G7254HHA	1.5V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-8500	CL7 (7-7-7)
VR7EL4G7254HHD	1.5V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-10600	CL9 (9-9-9)
VR7EL4G7254HHF	1.5V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-12800	CL11 (11-11-11)
VR7EL4G7254HEZ	1.5V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-6400	CL6 (6-6-6)
VR7EL4G7254HEA	1.5V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-8500	CL7 (7-7-7)
VR7EL4G7254HED	1.5V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-10600	CL9 (9-9-9)
VR7EL4G7254HEF	1.5V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-12800	CL11 (11-11-11)
VR7EL2G7294GHZ	1.35V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-6400	CL6 (6-6-6)
VR7EL2G7294GHA	1.35V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-8500	CL7 (7-7-7)
VR7EL2G7294GHD	1.35V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-10600	CL9 (9-9-9)
VR7EL2G7294GHF	1.35V	16GB	2Gx72	512Mx4 (72)	BGA stack	4	PC3-12800	CL11 (11-11-11)
VR7EL4G7294HHZ	1.35V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-6400	CL6 (6-6-6)
VR7EL4G7294HHA	1.35V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-8500	CL7 (7-7-7)
VR7EL4G7294HHD	1.35V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-10600	CL9 (9-9-9)
VR7EL4G7294HHF	1.35V	32GB	4Gx72	1Gx4 (72)	BGA stack	4	PC3-12800	CL11 (11-11-11)
VR7EL4G7294HEZ	1.35V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-6400	CL6 (6-6-6)
VR7EL4G7294HEA	1.35V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-8500	CL7 (7-7-7)
VR7EL4G7294HED	1.35V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-10600	CL9 (9-9-9)
VR7EL4G7294HEF	1.35V	32GB	4Gx72	2Gx4 (36)	DDP	4	PC3-10600	CL11 (11-11-11)

Features

- JEDEC Standard Power
 - DDR3: VDD = VDDQ = 1.5V ± 5%
 - DDR3L: VDD = VDDQ = 1.35V ± 5%
 - 1.35V Backwards compatible to 1.5V VDD
 - VDDSPD = +3.30V ± 10%
- 240-pin Load-Reduced Dual-In-Line Memory Module with parity bit for address and control bus
- Onboard Integrated Memory Buffer (iMB)
- Multi-rank DIMM with single terminated load on all signals
- Programmable CAS Latency: 6, 7, 8, 9, 10
- Programmable CAS Write Latency (CWL).
- Programmable Additive Latency (Posted CAS).
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the mode register set (MRS)
- Selectable BC4 or BL8 on-the-fly (OTF)
- On-Die-Termination (ODT) and Dynamic ODT for improved signal integrity
- Refresh, Self Refresh and Power Down Modes
- ZQ Calibration for output driver and ODT
- System Level Timing Calibration Support via Write Leveling and Multi Purpose Register (MPR) Read Pattern.
- Serial Presence Detect with EEPROM
- Two On-DIMM Thermal Sensors
- Asynchronous Reset
- Supports ECC error detection and correction
- LRDIMM dimensions (JEDEC MO-269)
- RoHS Compliant

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 4 of 20

Nomenclature

Module Standard	SDRAM Standard	Clock
PC3-6400	DDR3-800	400MHz
PC3 -8500	DDR3-1066	533MHz
PC3-10600	DDR3-1333	667MHz
PC3-12800	DDR3-1600	800MHz

Addressing

Parameter	16GB	32GB
Refresh count	8K	8K
Row address	32K A[14:0]	64K A[15:0]
Device bank address	8 BA[2:0]	8 BA[2:0]
Column address	1K A[9:0]	1K A[9:0]

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 5 of 20

PIN CONFIGURATIONS

Pin	Front Side	Pin	Back Side	Pin	Front Side	Pin	Back Side	Pin	Front Side	Pin	Back Side	Pin	Front Side	Pin	Back Side
1	VREFDQ	121	VSS	31	DQ25	151	VSS	61	A2	181	A1	91	DQ41	211	VSS
2	VSS	122	DQ4	32	VSS	152	DQS12	62	VDD	182	VDD	92	VSS	212	DQS14
3	DQ0	123	DQ5	33	DQS3#	153	DQS12#	63	NC*	183	VDD	93	DQS5#	213	DQS14#
4	DQ1	124	VSS	34	DQS3	154	VSS	64	NC*	184	CK0	94	DQS5	214	VSS
5	VSS	125	DQS9	35	VSS	155	DQ30	65	VDD	185	CK0#	95	VSS	215	DQ46
6	DQS0#	126	DQS9#	36	DQ26	156	DQ31	66	VDD	186	VDD	96	DQ42	216	DQ47
7	DQS0	127	VSS	37	DQ27	157	VSS	67	VREFCA	187	EVENT#, NC	97	DQ43	217	VSS
8	VSS	128	DQ6	38	VSS	158	CB4	68	Par_In	188	A0	98	VSS	218	DQ52
9	DQ2	129	DQ7	39	CB0	159	CB5	69	VDD	189	VDD	99	DQ48	219	DQ53
10	DQ3	130	VSS	40	CB1	160	VSS	70	A10 / AP	190	BA1	100	DQ49	220	VSS
11	VSS	131	DQ12	41	VSS	161	DQS17	71	BA0	191	VDD	101	VSS	221	DQS15
12	DQ8	132	DQ13	42	DQS8#	162	DQS17#	72	VDD	192	RAS#	102	DQS6#	222	DQS15#
13	DQ9	133	VSS	43	DQS8	163	VSS	73	WE#	193	S0#	103	DQS6	223	VSS
14	VSS	134	DQS10	44	VSS	164	CB6	74	CAS#	194	VDD	104	VSS	224	DQ54
15	DQS1#	135	DQS10#	45	CB2	165	CB7	75	VDD	195	ODT0	105	DQ50	225	DQ55
16	DQS1	136	VSS	46	CB3	166	VSS	76	S1#	196	A13	106	DQ51	226	VSS
17	VSS	137	DQ14	47	VSS	167	NC(TEST)	77	ODT1	197	VDD	107	VSS	227	DQ60
18	DQ10	138	DQ15	48	VTT	168	RESET#	78	VDD	198	S3#	108	DQ56	228	DQ61
19	DQ11	139	VSS	KEY				79	S2#	199	VSS	109	DQ57	229	VSS
20	VSS	140	DQ20	49	VTT	169	CKE1	80	VSS	200	DQ36	110	VSS	230	DQS16
21	DQ16	141	DQ21	50	CKE0	170	VDD	81	DQ32	201	DQ37	111	DQS7#	231	DQS16#
22	DQ17	142	VSS	51	VDD	171	A15	82	DQ33	202	VSS	112	DQS7	232	VSS
23	VSS	143	DQS11	52	BA2	172	A14	83	VSS	203	DQS13	113	VSS	233	DQ62
24	DQS2#	144	DQS11#	53	Err_Out#	173	VDD	84	DQS4#	204	DQS13#	114	DQ58	234	DQ63
25	DQS2	145	VSS	54	VDD	174	A12 / BC#	85	DQS4	205	VSS	115	DQ59	235	VSS
26	VSS	146	DQ22	55	A11	175	A9	86	VSS	206	DQ38	116	VSS	236	VDDSPD
27	DQ18	147	DQ23	56	A7	176	VDD	87	DQ34	207	DQ39	117	SA0	237	SA1
28	DQ19	148	VSS	57	VDD	177	A8	88	DQ35	208	VSS	118	SCL	238	SDA
29	VSS	149	DQ28	58	A5	178	A6	89	VSS	209	DQ44	119	SA2	239	VSS
30	DQ24	150	DQ29	59	A4	179	VDD	90	DQ40	210	DQ45	120	VTT	240	VTT
				60	VDD	180	A3								

Note: All pins functionally the same as a DDR3 RDIMM, except for CK1/CK1# at pins 63 and 64, which are not needed for the LRDIMM.

Datasheet	10/21/2016
PS7ELXX72X4HXH	Viking Technology
Revision B	Page 6 of 20

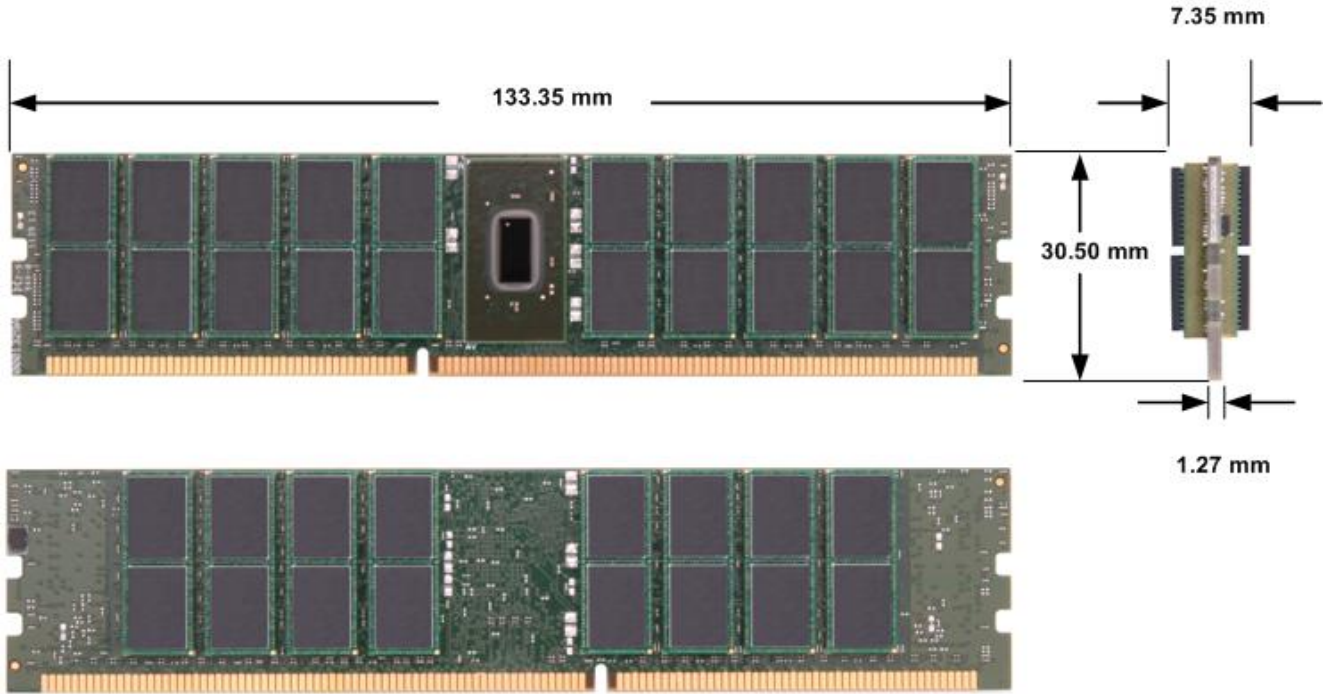
PIN FUNCTION DESCRIPTION

SYMBOL	TYPE	POLARITY	DESCRIPTION
CK0/ CK0#	IN		Differential pair of system clock inputs that drives input to iMB.
CKE[1:0]	IN	Active High	CKE HIGH activates, and CKE LOW deactivates internal clock signals, and device input buffers and output drivers of the SDRAMs. Taking CKE LOW provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), or ACTIVE POWER DOWN (row ACTIVE in any bank)
S[3:0]#	IN	Active Low	Module rank addressing chip selects: Enables the associated SDRAM command decoder when low and disables decoder when high. When decoder is disabled, new commands are ignored and previous operations continue. These input signals also disable all outputs (except CKE and ODT) of the memory buffer on the DIMM when both inputs are high. When both S[1:0] are high, all memory buffer outputs (except CKE, ODT and Chip select) remain in the previous state. S[3:2] operate similarly to S[1:0]
ODT[1:0]	IN	Active High	On-Die Termination control signals
RAS#, CAS#, WE#	IN	Active Low	When sampled at the positive rising edge of the clock, CAS#, RAS#, and WE# define the operation to be executed by the SDRAM.
VREFDQ	Supply		Reference voltage for DQ0-DQ63 and CB0-CB7.
VREFCA	Supply		Reference voltage for A0-A15, BA0-BA2, RAS#, CAS#, WE#, S0#, S1#, CKE0, CKE1, Par_In, ODT0 and ODT1.
BA[2:0]	IN	-	Selects which SDRAM bank of eight is activated. BA0 - BA2 define to which bank an Active, Read, Write or Precharge command is being applied. Bank address also determines mode register is to be accessed during an MRS cycle.
A[15:13, 12/BC, 11, 10/AP, 9:0]	IN	-	Provided the row address for Active commands and the column address and Auto Precharge bit for Read/Write commands to select one location out of the memory array in the respective bank. A10 is sampled during a Precharge command to determine whether the Precharge applies to one bank (A10 LOW) or all banks (A10 HIGH). If only one bank is to be precharged, the bank is selected by BA. A12 is also utilized for BL 4/8 identification for "BL on the fly" during CAS# command. The address inputs also provide the op-code during Mode Register Set commands.
DQ [63:0], CB [7:0]	I/O	-	Data and Check Bit Input/Output pins
VDD, VSS	Supply	-	Power and ground for the DDR SDRAM input buffers and core logic.
DM [8:0]	IN	Active High	Masks write data when high, issued concurrently with input data.
VDD, VSS	Supply		Power and ground for the DDR SDRAM input buffers and core logic.
VTT	Supply		Termination Voltage for Address/Command/Control/Clock nets.
DQS[17:0] DQS [17:0]#	I/O		Differential data strobe for input and output data.
SA [2:0]	IN	-	These signals are tied at the system planar to either VSS or VDDSPD to configure the serial SPD EEPROM address range.
SDA	I/O	-	This bidirectional pin is used to transfer data into or out of the SPD EEPROM. A resistor must be connected from the SDA bus line to VDDSPD on the system planar to act as a pullup.
SCL	IN	-	This signal is used to clock data into and out of the SPD EEPROM. A resistor may be connected from the SCL bus line to VDDSPD on the system planar to act as a pullup. (i.e. temperature sensing data)
EVENT#	OUT (open drain)	Active Low	This signal indicates that a thermal event has been detected in the thermal sensing device. The system should guarantee the electrical level requirement is met for the EVENT pin on TS/SPD part or iMB
VDDSPD	Supply	-	Serial EEPROM positive power supply wired to a separate power pin at the connector which supports from 3.0 Volt to 3.6 Volt (nominal 3.3V) operation.
RESET#	IN		The RESET pin is connected to the RST pin on the memory buffer. When low, all memory buffer outputs will be driven low and the clocks to the DRAMs will be set to low level
Par_In	IN		Parity bit for the Address and Control bus. ("1 " : Odd, "0 " : Even)
Err_Out#	OUT		Parity error found in the Address and Control bus
TEST			Used by memory bus analysis tools (unused (NC) on memory DIMMs)
NC			No Connect, Not used

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 7 of 20

MECHANICAL OUTLINE QUAD RANK

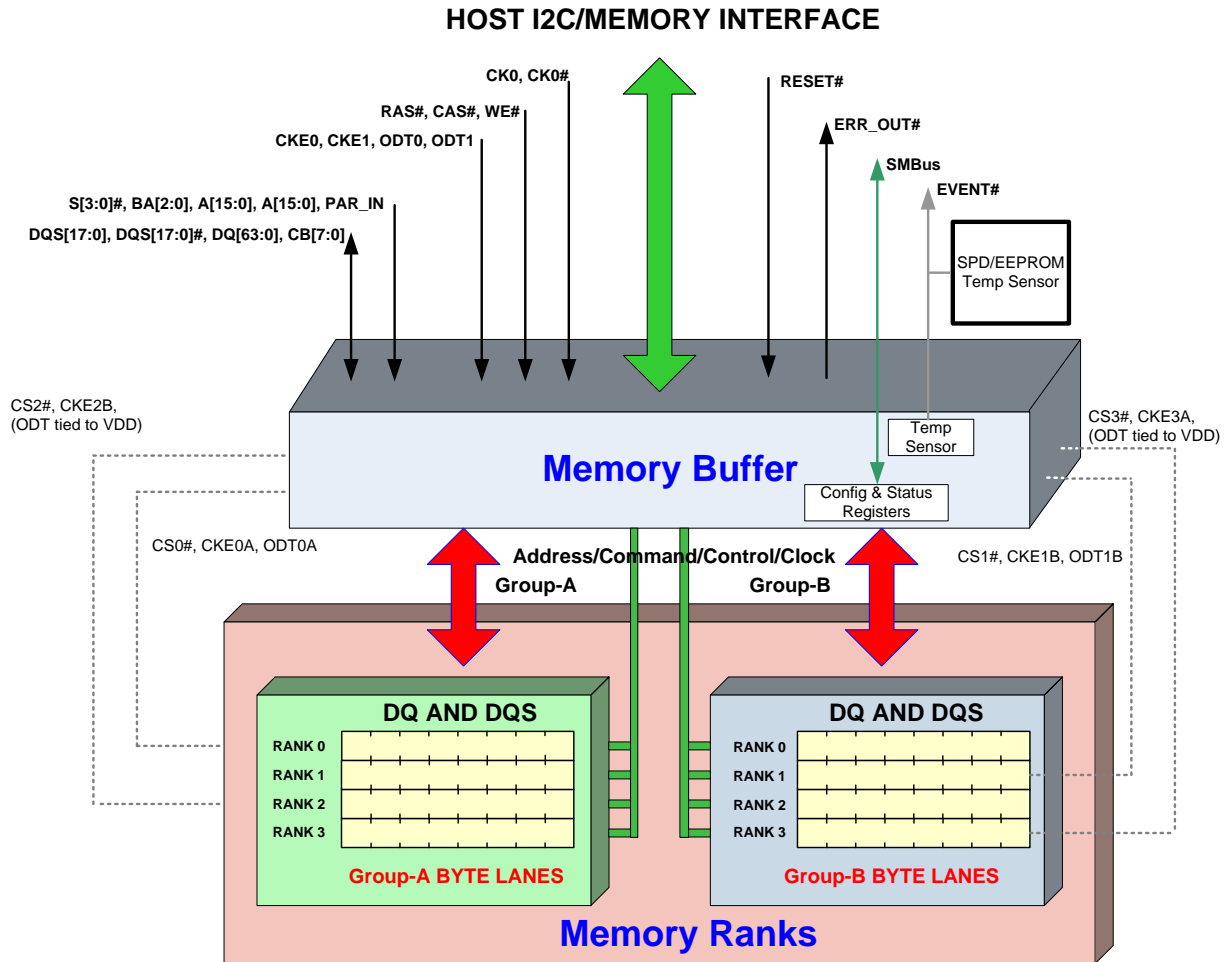
Dimensions are in millimeters. (Tolerance is +/- 0.0127, unless otherwise stated.)



Notes: Refer to JEDEC Standard Mechanical Outline MO-269 for other details

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 8 of 20

FUNCTIONAL BLOCK DIAGRAM QUAD RANK



DQ and DQS MAPPING ON THE HOST SIDE OF iMB

Byte Group	DQ								DQS			
	0	1	2	3	4	5	6	7	DQS0	DQS0#	DQS9	DQS9#
0	DQ0	DQ1	DQ2	DQ3	DQ4	DQ5	DQ6	DQ7	DQS0	DQS0#	DQS9	DQS9#
1	DQ8	DQ9	DQ10	DQ11	DQ12	DQ13	DQ14	DQ15	DQS1	DQS1#	DQS10	DQS10#
2	DQ16	DQ17	DQ18	DQ19	DQ20	DQ21	DQ22	DQ23	DQS2	DQS2#	DQS11	DQS11#
3	DQ24	DQ25	DQ26	DQ27	DQ28	DQ29	DQ30	DQ31	DQS3	DQS3#	DQS12	DQS12#
4	DQ32	DQ33	DQ34	DQ35	DQ36	DQ37	DQ38	DQ39	DQS4	DQS4#	DQS13	DQS13#
5	DQ40	DQ41	DQ42	DQ43	DQ44	DQ45	DQ46	DQ47	DQS5	DQS5#	DQS14	DQS14#
6	DQ48	DQ49	DQ50	DQ31	DQ52	DQ53	DQ54	DQ55	DQS6	DQS6#	DQS15	DQS15#
7	DQ56	DQ57	DQ58	DQ59	DQ60	DQ61	DQ62	DQ63	DQS7	DQS7#	DQS16	DQS16#
8	DQ64	DQ65	DQ66	DQ67	DQ68	DQ69	DQ70	DQ71	DQS8	DQS8#	DQS17	DQS17#

OVERVIEW OF LRDIMM MODULE OPERATION

The Load Reduced DIMM (LRDIMM) has the same memory interface as the JEDEC standard DDR3 RDIMM but unlike a DDR3 Register DIMM which only buffers the Command, Address, Control and Clock, the LRDIMM provides additional buffering for the Data (DQ) interface between the Memory Controller and the DRAM components. The onboard Integrated Memory Buffer (iMB) on each LRDIMM enables larger memory capacities at higher memory bandwidths by providing a single load per signal, per module, for all address, control, DQ and DQS nodes and reduces the capacitive loading on the memory channel data bus.

Similar to DDR3 RDIMM's, the clock, control, command, and address buses are routed in a fly-by topology, where each clock, control, command, and address pin on each DRAM is connected to a single trace and terminated. This differs from the tree structure of the DDR2 technology, where the termination is off the module near the connector). Inherent in the fly-by topology, the timing skew between the clock and DQS signals can be easily accounted for by using the same write-leveling feature of DDR3 RDIMM's. The LRDIMM uses a DQS/DQS# differential pair to capture data and CK/CK# differential pair to capture commands, addresses, and control signals. The data strobes and differential clocks ensure noise immunity by providing precise crossing points to capture the input signals.

The iMB supports 8-bank DRAM using a DDR3 8n prefetch architecture which transfers two data words per clock cycle at the I/O pins. A single read or write access for the DRAM module consists of a single 8n-bit-wide, one-clock-cycle data transfer at the internal DRAM core and eight corresponding n-bit-wide, one-half-clock-cycle data transfers at the I/O pins.

All memory control for the DRAM resides in the host, including memory request initiation, timing, scrubbing and power management. The iMB handles memory requests to and from the local DIMM by using control and status registers that are accessible through the SMBus, as well as through in-band channel commands. These registers can be read by software from the SMBus host any time the memory buffer is powered, except when the memory buffer is in clock-stopped power-down mode, or when the device RESET# pin is asserted. There are 3 types of LRDIMM resets:

- 1) SMBus reset which affect only the SMBus interface.
- 2) Soft reset generated by setting control word F2RC1, DA3 to '1'.
- 3) Hard reset when the RESET# signal is low.

RESET# is initiated by the host. It can be asynchronous to the clock including power up or in the middle of DRAM commands. Under these conditions, the iMB will be reset and the contents of DRAM memory are not guaranteed. Upon assertion of RESET#:

- All input receivers are disabled, and can be left floating.
- DRAM CKE and RESET# are driven LOW asynchronously.
- DQ/DQS are don't care. All DRAM C/A inputs (except CKE) are floated.
- DRAM CK/CK# are floated.
- All Configuration and Status Register (CSR) bits are set to their default values.
- All Control Word registers are restored to their default states.
- All internal state machines are put in their default state.
- The "sticky bits" are cleared in the iMB registers that hold the results of the DRAM interface training.

The host can initiate multiple soft resets if needed during LRDIMM initialization and the settings that were established during previous DRAM interface training will not be cleared.

The iMB can accept parity bits from the host memory controller. Even parity is calculated from all cmd and address signals (Note CKE, ODT, and S# are not included in parity). The last bit of the sum is compared to the parity signal provided by the system at the Par_In pin. Parity errors are flagged on the Err_Out# pin and checked during control-word programming.

There are 2 temperature sensors on the LRDIMM. A class-C temperature sensor is located within the memory buffer to monitor the temperature of the iMB and will assert the EVENT# pin if the temperature thresholds are exceeded. This temperature sensor is accessible through the SMBus. The second temperature sensor is a class-B temperature sensor

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 10 of 20

integrated with the SPD EEPROM to monitor the module temperature using a conductive pad under the EEPROM. The EEPROM temperature is converted into a digital word via the SMBus. There are user-programmable registers on the EEPROM to create unique temperature-sensing solutions based on system requirements. Programming and configuration details comply with JEDEC standard No. 21-C. All other SPD EEPROM functionally is the same as JEDEC standard DDR3 RDIMMs. The lower 128 bytes of data is programmed to comply with JEDEC standard JC-45 to contain the characteristics of the DIMM and the upper 128 bytes contain vendor specific information.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Voltage on any pin relative to GND		-0.4 ~ 1.975	V
Voltage on VDD supply relative to GND	VDD	-0.4 ~ 1.975	V
Voltage on VDDQ supply relative to GND	VDDQ	-0.4 ~ 1.975	V
Voltage on VDDSPD supply relative to GND	VDDSPD	-0.5 to +6.5	V
Storage temperature	TSTG	-55 ~ +100	°C

Note: Permanent device damage may occur if 'ABSOLUTE MAXIMUM RATINGS' are exceeded. Functional operation should be restricted to recommended operating condition. Exposure to higher than recommended voltage for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS AND CHARACTERISTICS (SSTL_1.5)

Recommended operating conditions: Voltages referenced to GND, Module Ambient = 0 to 70°C

Parameter	Symbol	Min	Max	Unit	Notes
DRAM Case Temperature	DRAM Tcase	0	95	°C	5
Supply voltage (1.5V ± 5%)	VDD	1.425	1.575	V	1, 2
Supply voltage for DQ, DQS @ 1.5V	VDDQ	1.425	1.575	V	1, 2
Supply voltage (1.35V ± 5%)	VDD	1.283	1.45	V	1, 2
Supply voltage for DQ, DQS @ 1.35V	VDDQ	1.283	1.45	V	1, 2
Reference Voltage for DQ, DM inputs	VREFDQ(DC)	0.49 x VDD	0.51 x VDD	V	3, 4
Reference Voltage for ADD, CMD inputs	VREFCA(DC)	0.49 x VDD	0.51 x VDD	V	3, 4
Termination Reference Current	I _{VTT}	-600	600	mA	
Termination Voltage	V _{TT}	0.49 x VDD	0.51 x VDD	V	3, 4
EEPROM Supply Voltage: +3.30V ± 10%	VDDSPD	2.97	3.63	V	
Input high voltage	V _{IH} (AC)	VREF + 0.175	-	V	
	V _{IH} (DC)	VREF + 0.100	VDD		
Input low voltage	V _{IL} (AC)	-	VREF - 0.175	V	
	V _{IL} (DC)	VSS	VREF - 0.100		

Notes:

- VDDQ tracks with VDD. VDDQ must be less than or equal to VDD. AC parameters are measured with VDD and VDDQ tied together.
- The ac peak noise on VREF may not allow VREF to deviate from VREF.DC by more than ±1% VDD (for reference: approx. ± 15 mV).
- For reference: approx. VDD/2 ± 15 mV.
- Refresh rate required to be doubled (tREFI = 3.9µs) when 85°C < TC < 95°C.

Datasheet	10/21/2016
PS7ELXX72X4XH	Viking Technology
Revision B	Page 11 of 20

iMB SPECIFICATIONS

Symbol	Parameter	Signals	Min	Nom	Max	Unit
	DC Supply voltage (DDR3)	VDD, VDDA, VDDP	1.425	1.5	1.575	V
	DC Supply voltage (DDR3L)	VDD, VDDA, VDDP	1.283	1.35	1.451	V
VCCSPD	SMBus Interface Supply voltage	VCCSPD	3	3.3	3.6	V
V _{REF}	DC Reference voltage		0.49 x V _{DD}	0.50 x V _{DD}	0.51 x V _{DD}	V
V _{TT}	DC Termination voltage ¹		V _{REF} - 40 mV	V _{REF}	V _{REF} + 40 mV	V
V _{IH(AC)}	AC HIGH-level input voltage (DDR3)	CMD/ADD/CTRL inputs ²	V _{REF} + 0.1	-	V _{DD} + 0.4	V
V _{IL(AC)}	AC LOW-level input voltage (DDR3)	CMD/ADD/CTRL inputs	-0.4	-	V _{REF} - 0.1	V
V _{IH(DC)}	DC HIGH-level input voltage (DDR3)	CMD/ADD/CTRL inputs	V _{REF} + 0.1	-	V _{DD}	V
V _{IL(DC)}	DC LOW-level input voltage (DDR3)	CMD/ADD/CTRL inputs	V _{SS}	-	V _{REF} - 0.1	V
V _{IH(AC)_DQ}	AC HIGH-level input voltage (DDR3)	DQ inputs	V _{REF} + 0.1	-	V _{DD} + 0.4	V
V _{IL(AC)_DQ}	AC LOW-level input voltage (DDR3)	DQ inputs	-0.4	-	V _{REF} - 0.1	V
V _{IH(DC)_DQ}	DC HIGH-level input voltage (DDR3)	DQ inputs	V _{REF} + 0.1	-	V _{DD}	V
V _{IL(DC)_DQ}	DC LOW-level input voltage (DDR3)	DQ inputs	V _{SS}	-	V _{REF} - 0.1	V
V _{IH(AC)}	AC HIGH-level input voltage (DDR3L)	CMD/ADD/CTRL inputs	V _{REF} + 0.09	-	V _{DD} + 0.2	V
V _{IL(AC)}	AC LOW-level input voltage (DDR3L)	CMD/ADD/CTRL inputs	-0.2	-	V _{REF} - 0.09	V
V _{IH(DC)}	DC HIGH-level input voltage (DDR3L)	CMD/ADD/CTRL inputs	V _{REF} + 0.09	-	V _{DD}	V
V _{IL(DC)}	DC LOW-level input voltage (DDR3L)	CMD/ADD/CTRL inputs	V _{SS}	-	V _{REF} - 0.09	V
V _{IH(AC)_DQ}	AC HIGH-level input voltage (DDR3L)	DQ inputs	V _{REF} + 0.09	-	V _{DD} + 0.2	V
V _{IL(AC)_DQ}	AC LOW-level input voltage (DDR3L)	DQ inputs	-0.2	-	V _{REF} - 0.09	V
V _{IH(DC)_DQ}	DC HIGH-level input voltage (DDR3L)	DQ inputs	V _{REF} + 0.09	-	V _{DD}	V
V _{IL(DC)_DQ}	DC LOW-level input voltage (DDR3L)	DQ inputs	V _{SS}	-	V _{REF} - 0.09	V
V _{IH(CMOS)}	HIGH-level input voltage	RESET#	0.65 x V _{DD}	-	V _{DD}	V
V _{IL(CMOS)}	LOW-level input voltage	RESET#	0	-	0.35 x V _{DD}	V
V _{IL (Static)}	Static LOW-level input voltage ³	CK, CK#	-	-	0.35 x V _{DD}	V
V _{IX(AC)}	Differential input crosspoint voltage range	CK, CK#	0.5xV _{DD} - 0.2	0.5 x V _{DD}	0.5xV _{DD} + 0.2	V
V _{ID(AC)}	Differential input voltage ⁴ (DDR3)	CK, CK#	0.2	-	V _{DD}	V
V _{ID(AC)}	Differential input voltage ^d (DDR3L)	CK, CK#	0.18	-	V _{DD}	V
V _{IX(AC)_DQ_s}	Differential input crosspoint voltage range	DQS, DQS#	0.5xV _{DD} - 0.2	0.5 x V _{DD}	0.5xV _{DD} + 0.2	V
V _{ID(AC)_DQ_s}	Differential input voltage ⁵ (DDR3)	DQS, DQS#	0.2	-	V _{DD}	V
V _{ID(AC)_DQ_s}	Differential input voltage ⁶ (DDR3L)	DQS, DQS#	0.18	-	V _{DD}	V
I _{OH}	HIGH-level output current ⁶	All CA outputs	-11	-	-	mA
I _{OL}	LOW-level output current	All CA outputs	11	-	-	mA
I _{OH}	HIGH-level output current	All DQ outputs	-10.7	-	-	mA
I _{OL}	LOW-level output current	All DQ outputs	10.7	-	-	mA
I _{OL_ERROUT}	LOW-level output current	Err_Out#	25	-	-	mA
I _{OL_EVENT}	LOW-level output current	EVENT	25	-	-	mA
V _{OD}	Differential re-driven clock swing	Yn, Yn#	0.45	-	V _{DD}	V

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 12 of 20

Symbol	Parameter	Signals	Min	Nom	Max	Unit
V _{OX}	Differential output crosspoint voltage	DQS, DQS#	0.5xV _{DD} - 0.09	-	0.5xV _{DD} + 0.09	V
T _{case (max)}	iMB Case temperature ⁷	-	-	-	125 ^{note8}	°C
V _{OL_ERROU} T	Output LOW voltage (Err_Out# pin)	IOL = 25 mA	-	-	0.4	v
V _{OL_EVENT}	Output LOW voltage (EVENT pin)	IOL = 25 mA	-	-	0.4	v
I _{I_RST}	Input current for RESET# pin	RESET#, VI = VDD or GND	-	-	±5	µA
I _{ID}	Input current for CMD, ADD, CNTRL and PAR_IN input pins	Data inputs1, VI = VDD or GND	-	-	±5	µA
I _{I_CK}	Input current for CK and CK# input pins	CK, CK#2; VI = VDD or GND	-5	-	150	µA

Notes:

1. VTT supply voltage specification is for DRAM portion of the LRDIMM (QCMD/QADDR/QCTRL/Yn/Yn# only;
2. DCKE[2:0], DCKE[3]/DODT[1], DODT[0], DA0..DA15, DBA0..DBA2, DRAS#, DCAS#, DWE#, PAR_IN, DCS[7:0]#;
3. This specification applies only when both CK and CK# are actively driven LOW. It does not apply when CK/CK# are floating.
4. VID is the magnitude of the difference between the input level on CK and the input level on CK#.
5. VID_DQS is the magnitude of the difference between the input level on DQS and the input level on DQS#.
6. Default settings
7. Measurement procedure JESD51-2
8. Since iMB silicon is bare die on FBGA package, the assumption is Tcase (max) is very close to silicon Tj (max). Hence, tcase (max) of 125 °C is used for all speed grades.
9. Spec value is for each pin

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 13 of 20

DC CHARACTERISTICS DEFINITIONS (Recommended operating conditions unless otherwise noted, Tcase = 0 to 95 °C)

Symbol	Conditions	Units	Notes
IDD0	Operating one bank active-precharge current; tCK = tCK(IDD), tRC = tRC(IDD), tRAS = tRASmin(IDD); CKE is HIGH, CS is HIGH between valid commands; Address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 2
IDD1	Operating one bank active-read-precharge current; IOUT = 0mA; BL = 8, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRC = tRC(IDD), tRAS = tRASmin(IDD), tRCD = tRCD(IDD); CKE is HIGH, CS is HIGH between valid commands; Address bus inputs are SWITCHING; Data pattern is same as IDD4W	mA	1, 2
IDD2P-S	Precharge power-down current (slow exit); All banks idle; tCK = tCK(IDD); CKE is LOW; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3
IDD2P-F	Precharge power-down current (fast exit); All banks idle; tCK = tCK(IDD); CKE is LOW; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3
IDD2Q	Precharge quiet standby current; All banks idle; tCK = tCK(IDD); CKE is HIGH, CS is HIGH; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3
IDD2N	Precharge standby current; All banks idle; tCK = tCK(IDD); CKE is HIGH, CS is HIGH; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3
IDD3P	Active power-down current; All banks open; tCK = tCK(IDD); CKE is LOW; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3
IDD3N	Active standby current; All banks open; tCK = tCK(IDD), tRAS = tRASmax(IDD), tRP = tRP(IDD); CKE is HIGH, CS is HIGH between valid commands; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3
IDD4W	Operating burst write current; All banks open, Continuous burst writes; BL = 8, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRAS = tRASmax(IDD), tRP = tRP(IDD); CKE is HIGH, CS is HIGH between valid commands; Address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 2
IDD4R	Operating burst read current; All banks open, Continuous burst reads, IOUT = 0mA; BL = 8, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRAS = tRAS-max(IDD), tRP = tRP(IDD); CKE is HIGH, CS is HIGH between valid commands; Address bus inputs are SWITCHING; Data pattern is same as IDD4W	mA	1, 2
IDD5B	Burst refresh current; tCK = tCK(IDD); Refresh command at every tRFC(IDD) interval; CKE is HIGH, CS is HIGH between valid commands; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3
IDD6	Self refresh current; CK and CK at 0V; CKE ≤ 0.2V; Other control and address bus inputs are FLOATING; Data bus inputs are FLOATING	mA	1, 3
IDD6ET	Extended Temperature Range Self-Refresh Current; CK and CK at 0V; CKE ≤ 0.2V; Other control and address inputs are FLOATING; Data Bus inputs are FLOATING, PASR disabled, Applicable for MR2 setting A6=0 and A7=1	mA	1, 3
IDD7	Operating bank interleave read current; All bank interleaving reads, IOUT = 0mA; BL = 8, CL = CL(IDD), AL = tRCD(IDD)-1*tCK(IDD); tCK = tCK(IDD), tRC = tRC(IDD), tRRD = tRRD(IDD), tRCD = 1*tCK(IDD); CKE is HIGH, CS is HIGH between valid commands; Address bus inputs are STABLE during DESELECTS; Data pattern is same as IDD4R;	mA	1, 2

Notes:

- 1) Calculated values are from component data.
- 2) One module rank in the active IDD; the other ranks in IDD2P-S (slow exit)
- 3) All ranks in this IDD condition.

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 14 of 20

IDD CURRENT

DC CHARACTERISTICS CURRENTS QUAD RANK 2Gbit

Symbol	DDR3-800	DDR3-1066	DDR3-1333	Unit
IDD0	TBD	TBD	TBD	mA
IDD1	TBD	TBD	TBD	mA
IDD2P-S	TBD	TBD	TBD	mA
IDD2P-F	TBD	TBD	TBD	mA
IDD2Q	TBD	TBD	TBD	mA
IDD2N	TBD	TBD	TBD	mA
IDD3P	TBD	TBD	TBD	mA
IDD3N	TBD	TBD	TBD	mA
IDD4R	TBD	TBD	TBD	mA
IDD4W	TBD	TBD	TBD	mA
IDD5B	TBD	TBD	TBD	mA
IDD6	TBD	TBD	TBD	mA
IDD6ET	TBD	TBD	TBD	mA
IDD7	TBD	TBD	TBD	mA

DC CHARACTERISTICS CURRENTS QUAD RANK 4Gbit

Symbol	DDR3-800	DDR3-1066	DDR3-1333	Unit
IDD0	TBD	TBD	TBD	mA
IDD1	TBD	TBD	TBD	mA
IDD2P-S	TBD	TBD	TBD	mA
IDD2P-F	TBD	TBD	TBD	mA
IDD2Q	TBD	TBD	TBD	mA
IDD2N	TBD	TBD	TBD	mA
IDD3P	TBD	TBD	TBD	mA
IDD3N	TBD	TBD	TBD	mA
IDD4R	TBD	TBD	TBD	mA
IDD4W	TBD	TBD	TBD	mA
IDD5B	TBD	TBD	TBD	mA
IDD6	TBD	TBD	TBD	mA
IDD6ET	TBD	TBD	TBD	mA
IDD7	TBD	TBD	TBD	mA

CAPACITANCE

Symbol	Parameter	Conditions	Min	Max	Unit
C _I	Input capacitance, CA and CTRL inputs (with any IBT ³)	See Notes 1 and 2	0.7	- 1.2	pF
C _{CK}	Input capacitance, CK, CK#	See Note 1	0.7	- 1.2	pF
C _{IO}	Input/output capacitance	DQ, DQS and DQS#	1.4	- 2.1	pF
C _{IR}	Input capacitance, RESET#	V _I = V _{DD} or GND; V _{DD} = 1.5V	-	- 3	pF

Notes:

1. This parameter is not subject to production test. It is verified by design and characterization. The capacitance is measured according to JEP147("PROCEDURE FOR MEASURING INPUT CAPACITANCE USING A VECTOR NETWORK ANALYZER(VNA)") with VDD, VSS applied and all other pins floating (except the pin under test, DCKE[2:0], DCKE[3]/DODT[1], RESET# and ODT[0] as necessary). VDD=1.5V/1.35V, VBIAS=VDD/2 and on-die termination off. The specified values are on die cap only, and not including the package cap.
2. Data inputs are DCKE[2:0], DCKE[3]/DODT[1], DODT[0], DA0..DA15, DBA0..DBA2, DRAS#, DCAS#, DWE#, PAR_IN, DCS[7:0]#
3. Input Bus Termination on the command/address and control input-only pins on the iMB

DC and AC Specifications for the SMBus Interface

The specifications for the SMBus follow industry standards.

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 15 of 20

Host Interface Termination Specifications

CMD/ADDR/CTRL Input Bus Termination Requirement

Symbol	Parameter	DDR3/DDR3L -800/1066/1333/1600			Unit
		Min	Typ	Max	
IBT ₍₃₀₀₎	Termination resistance	270	300	330	Ω
IBT ₍₂₀₀₎	Termination resistance	180	200	220	Ω
IBT ₍₁₅₀₎	Termination resistance	135	150	165	Ω
IBT ₍₁₀₀₎	Termination resistance	90	100	110	Ω
IBT _{TOL}	Termination tolerance ¹	-10	-	10	%
ΔV _M	Deviation of V _M w.r.t. V _{DD} /2 ³	-	-	2.5	%

Notes:

1) Tolerance is defined as the deviation from the nominal value of the small signal input resistance. Measured from 0.2*V_{DD} to 0.8*V_{DD}

2) Measure voltage (V_{OUT} = V_M) at test pin with no load (I_{OUT} = 0). ΔV_M = |2 * V_M/V_{DD} - 1| * 100%.

Host Interface Input Timing and DQ/DQS Output Timing

This section specifies various input timing for command/Address/Control/Clock, DQ/DQS, C/A setup and hold, Data setup and hold, initialization, control word write, power-down, write leveling, and RTT. In addition, it also covers DQ/DQS timing.

Host Interface Input Timing Parameters

Symbol	Parameter	DDR3- 800		DDR3-1066		DDR3-1333		DDR3-1600		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Input Clock Timing										
f _{clock}	Input clock frequency	300	810	300	810	300	810	300	810	MHz
f _{TEST}	Input clock frequency	70	300	70	300	70	300	70	300	MHz
t _{CH} /t _{CL}	Pulse duration, CK, CK# HIGH or LOW	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6	t _{CK} ¹
Initialization Timing										
t _{INIT}	Duration of reset after stable VDD	200	-	200	-	200	-	200	-	μs

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 16 of 20

Symbol	Parameter	DDR3- 800		DDR3-1066		DDR3-1333		DDR3-1600		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACT}	Time for VREF, DCKEx, DCSx to be stable before RESET# goes HIGH	8	-	8	-	8	-	8	-	t _{CK}
t _{STAB}	PLL lock time (for Application Frequency Only)	6	-	6	-	6	-	6	-	μs
t _{QVREF}	QVREFCA/QVREFDQ voltage stable till RESET# goes HIGH	1	-	1	-	1	-	1	-	μs
Control Word & DRAM MRS Write Timing										
t _{MWD}	Control word to control word (or next command) programming delay	16	-	16	-	16	-	16	-	t _{CK}
t _{DRAM_MRS}	DRAM MRS to MRS Command programming delay	6	-	6	-	6	-	6	-	t _{CK}
Power Down Timing										
t _{InDIS}	Input buffers (except for CK/CK#, DCKEn, DODTn and RESET#) disable time after DCKE[1:0] is LOW	1	4	1	4	1	4	1	4	t _{CK}
t _{QDIS}	Output buffers (except for Yn/Yn#, QxCKEn, QxODTn) hi-z after QxCKEn is driven LOW	1.5	1.5	1.5	1.5	1.5	1.5	1.5	1.5	t _{CK}
t _{CKoff}	Number of t _{CK} required for both DCKE0 and DCKE1 to remain LOW before both CK/CK# are driven LOW	5	-	5	-	5	-	5	-	t _{CK}
t _{CKEV}	Input buffers (DCKE0 and DCKE1) disable time after CK/CK# = LOW	2	-	2	-	2	-	2	-	t _{CK}
t _{Fixedoutput}	Static register output after DCKE0 or DCKE1 is HIGH at the input (exit from Power saving state)	1	3	1	3	1	3	1	4	t _{CK}

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 17 of 20

Symbol	Parameter	DDR3- 800		DDR3-1066		DDR3-1333		DDR3-1600		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
CMD/ADDR/CTL Inputs Timing										
tIS (AC100)	Setup time ² (DDR3)	100	-	100	-	100	-	100	-	ps
tIH (DC100)	Hold time ³ (DDR3)	100	-	100	-	100	-	100	-	ps
ODTH4	DODTn high time without write command or with write command and BC4	4	-	4	-	4	-	4	-	t _{CK}
ODTH8	DODTn high time without write command or with write command and BL8	8	-	8	-	8	-	8	-	t _{CK}
DQ Inputs Timing										
tDS (AC100)	Setup time ⁴ (DDR3)	45	-	45	-	30	-	30	-	ps
tDH (DC100)	Hold time ⁵ (DDR3)	45	-	45	-	30	-	30	-	ps
Data Strobe (DQS) Inputs Timing										
tWPRE	DQS, DQS# differential WRITE Preamble	0.9	-	0.9	-	0.9	-	0.9	-	t _{CK}
tWPST	DQS, DQS# differential WRITE Postamble	0.3	-	0.3	-	0.3	-	0.3	-	t _{CK}
tDQSL	DQS, DQS# differential input low pulse width	0.45	0.55	0.45	0.55	0.45	0.55	0.45	0.55	t _{CK}
tDQSH	DQS, DQS# differential input high pulse width	0.45	0.55	0.45	0.55	0.45	0.55	0.45	0.55	t _{CK}
tDQSS	DQS, DQS# rising edge to CK, CK# rising edge	-0.25	0.25	-0.25	0.25	-0.25	0.25	-0.27	0.27	t _{CK}
tDSS	DQS, DQS# falling edge setup time to CK, CK# rising edge	0.2	-	0.2	-	0.2	-	0.18	-	t _{CK}
tDSH	DQS, DQS# falling edge hold time to CK, CK# rising edge	0.2	-	0.2	-	0.2	-	0.18	-	t _{CK}
Write Leveling Inputs Timing										

Symbol	Parameter	DDR3- 800		DDR3-1066		DDR3-1333		DDR3-1600		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
tWLMRD	First DQS, DQS# rising edge after write leveling mode is programmed	40	-	40	-	40	-	40	-	nCK
tWLDQS EN	DQS, DQS# delay after write leveling mode is programmed	25	-	25	-	25	-	25	-	nCK
tWLS	Write leveling setup time from rising CK, CK# crossing to rising DQS, DQS# crossing	325	-	245	-	195	-	165	-	Ps
tWLH	Write leveling hold time from rising CK, CK# crossing to rising DQS, DQS# crossing	325	-	245	-	195	-	165	-	Ps
RTT Inputs Timing										
tAON	RTT turn-on	-400	400	-300	300	-250	250	-225	225	Ps
tAOF	RTT_Nom and RTT_WR turn-off time from ODTLoff reference	0.3	0.7	0.3	0.7	0.3	0.7	0.3	0.7	t _{CK}
tADC	RTT dynamic change skew	0.3	0.7	0.3	0.7	0.3	0.7	0.3	0.7	t _{CK}

- Notes:**
1. Clock cycle time
 2. Setup (t_S) nominal slew rate for a rising signal is defined as the slew rate between the last crossing of V_{REF(dc)} and first crossing of V_{IH(ac)min}. Setup (t_S) nominal slew rate for a falling signal is defined as the slew rate between the last crossing of V_{REF(dc)} and the first crossing of V_{IL(ac)max}. If the actual signal is always earlier than the nominal slew rate line between shaded 'V_{REF(dc)} to ac region', use nominal slew rate for derating value. If the actual signal is later than the nominal slew rate line anywhere between shaded 'V_{REF(dc)} to ac region', the slew rate of a tangent line to the actual signal from the ac level to V_{REF(dc)} level is used for derating value
 3. Hold (t_H) nominal slew rate for a rising signal is defined as the slew rate between the last crossing of V_{IL(dc)max} and the first crossing of V_{REF(dc)}. Hold (t_H) nominal slew rate for a falling signal is defined as the slew rate between the last crossing of V_{IH(dc)min} and the first crossing of V_{REF(dc)}. If the actual signal is always later than the nominal slew rate line between shaded 'dc level to V_{REF(dc)} region' use nominal slew rate for derating value. If the actual signal is earlier than the nominal slew rate line anywhere between shaded 'dc to V_{REF(dc)} region', the slew rate of a tangent line to the actual signal from the dc level to V_{REF(dc)} level is used for derating value.
 4. Setup (t_{DS}) nominal slew rate for a rising signal is defined as the slew rate between the last crossing of V_{REF(dc)} and first crossing of V_{IH(ac)min}. Setup (t_{DS}) nominal slew rate for a falling signal is defined as the slew rate between the last crossing of V_{REF(dc)} and the first crossing of V_{IL(ac)max}. If the actual signal is always earlier than the nominal slew rate line between shaded 'V_{REF(dc)} to ac region', use nominal slew rate for derating value. If the actual signal is later than the nominal slew rate line anywhere between shaded 'V_{REF(dc)} to ac region', the slew rate of a tangent line to the actual signal from the ac level to V_{REF(dc)} level is used for derating value.
 5. Hold (t_{DH}) nominal slew rate for a rising signal is defined as the slew rate between the last crossing of V_{IL(dc)max} and the first crossing of V_{REF(dc)}. Hold (t_{DH}) nominal slew rate for a falling signal is defined as the slew rate between the last crossing of V_{IH(dc)min} and the first crossing of V_{REF(dc)}. If the actual signal is always later than the nominal slew rate line between shaded 'dc level to V_{REF(dc)} region' use nominal slew rate for derating value. If the actual signal is earlier than the nominal slew rate line anywhere between shaded 'dc to V_{REF(dc)} region', the slew rate of a tangent line to the actual signal from the dc level to V_{REF(dc)} level is used for derating value.

Datasheet	10/21/2016
PS7ELXX72X4XHX	Viking Technology
Revision B	Page 19 of 20

Host Interface DQ/DQS Output Timing Parameters

Symbol	Parameter	DDR3-800		DDR3-1066		DDR3-1333		DDR3-1600		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
DQ Output Timing										
tDQSQ	DQS, DQS# to DQ skew, per byte group, per access ¹	-	150	-	125	-	100	-	85	Ps
tQH	DQ output hold time from DQS, DQS#	0.45	-	0.45	-	0.45	-	0.45	-	t _{CK} ²
Write Leveling Output Timing										
tWLO	Write leveling output delay	0	7.5	0	7.5	0	7.5	0	7.5	Ns
tWLOE	Write leveling output error	0	2	0	2	0	2	0	2	Ns
Data Strobe (DQS) Output Timing										
tRPRE	DQS, DQS# differential READ Preamble	0.9	-	0.9	-	0.9	-	0.9	-	t _{CK}
tRPST	DQS, DQS# differential READ Postamble	0.3	-	0.3	-	0.3	-	0.3	-	t _{CK}
tQSH	DQS, DQS# differential output high time	0.46	-	0.46	-	0.46	-	0.46	-	t _{CK}
tQSL	DQS, DQS# differential output low time	0.46	-	0.46	-	0.46	-	0.46	-	t _{CK}

Notes:

1. This skew represents the absolute output skew and contains the pad skew and package skew.
2. Clock cycle time

DRAM TIMING CHARACTERISTICS

Certain timing constraints need to be observed for sending commands to the DRAMs. The checking and optimizing of all the various timing requirements is simplified by the buffer observing the timing between two consecutive commands and refresh timing.

Datasheet	10/21/2016
PS7ELXX72X4XH	Viking Technology
Revision B	Page 20 of 20